

**AMENDMENTS**

Please amend the above application as indicated below.

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**In the Specification**

On pages 8-9, please replace paragraph [0037] with the following:

[0037] If circuits 39 are indeed located on the surface of the substrate 21, such circuits 39 may be covered with a ~~dialectric~~ dielectric layer or other type of insulating layer deposited on the substrate 21 before formation of the posts 27 and gasket 42. Such a layer will protect the circuits 39 from the processes used to form the posts 27 and gasket 42. To further protect such circuits when forming the posts 27 and gasket 42, processes that exceed acceptable temperature ranges for the circuits should be avoided.